



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani Art Unit : 1765
Serial No.: 09/596,755 Examiner : Robert Kunemund
Filed : June 15, 2000
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

BOX AF

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Official Action dated April 3, 2001,
Paper No. 6, in the above-referenced application, please amend
the above-identified application as follows:

In the Claims:

Please amend claims 2, 8, 14, 20, 22, 29, 36, and 41 as
follows:

2. (Amended) A method for manufacturing a semiconductor
device comprising steps of:

forming a semiconductor film over a substrate; and

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

Thereby certify under 37 CFR §1.8(a) that this correspondence is being
deposited with the United States Postal Service as first class mail with
sufficient postage on the date indicated below and is addressed to the

Susan Regan